

ABSTRACT

Broadly speaking, the invention pertains to substrates for use in semiconductor manufacturing. A peripheral ledge or similar structure can be provided in a die attach pad, so as to retain adhesive that may flow from the die support surface when the die is attached to the die attach pad. In this manner, adhesive is prevented from flowing off the die attach pad, where it can create unwanted conductive areas on the outer surface of an IC package. The accompanying reduction in area of the die support surface, and retention of adhesive from any downbond areas, also prevents delamination of the adhesive.